This product complies with the RoHS Directive (EU 2002/95/EC).

2PG009

Silicon N-channel enhancement IGBT

For plasma display panel drive For high speed switching circuits

■ Features

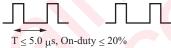
- \bullet Low collector-emitter saturation voltage: $V_{\text{CE(sat)}}\!<\!2.5~\text{V}$
- High-speed switching: $t_f = 185 \text{ ns (typ.)}$

■ Absolute Maximum Ratings $T_C = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|---------------------------------------|------------------|-------------|------|--|
| Collector-emitter voltage (E-B short) | V _{CES} | 510 | V | |
| Gate-emitter voltage (E-B short) | V _{GES} | -30 to +35 | V | |
| Collector current | I_{C} | 40 | A | |
| Peak collector current * | I _{CP} | 230 | A | |
| Danier dissination | D | 40 | W | |
| Power dissipation $T_a = 25^{\circ}C$ | P_{C} | 2.0 | W | |
| Junction temperature | T _j | 150 | °C | |
| Storage temperature | T _{stg} | -55 to +150 | °C | |

Note) *: Assurance of repetitive pulse. (Repetitive period $\leq 5 \mu s$ on-duty $\leq 20\%$)

But, it must stay within 40% of all that the time impressed pulse repetitively.



■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

| • Code |
|------------|
| TO-220D-A1 |

■ Package

- Marking Symbol: 2PG009
- Pin Name
 - 1. Gate
 - 2. Collector
 - 3. Emitter

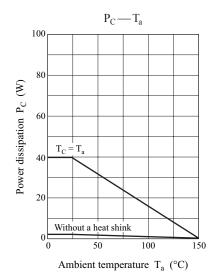
Internal Connection

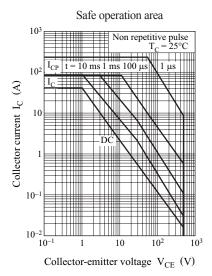


| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|-----------------------|--|------|------|------|------|
| Collector-emitter voltage (E-B short) | V _{CES} | $I_C = 1 \text{ mA}, V_{GE} = 0$ | 510 | | | V |
| Collector-emitter cutoff current (E-B short) * | I _{CES} | $V_{CE} = 408 \text{ V}, V_{GE} = 0$ | :(O) | | 5.0 | μΑ |
| Gate-emitter cutoff current (E-B short) | I_{GES} | $V_{GE} = \pm 35 \text{ V}, -30 \text{ V}, V_{CE} = 0$ | | | ±1.0 | μΑ |
| Gate-emitter threshold voltage | V _{GE(th)} | $V_{CE} = 10 \text{ V}, I_{C} = 1.0 \text{ mA}$ | 3.0 | | 5.5 | V |
| Collector-emitter saturation voltage | V _{CE(sat)} | $V_{GE} = 15 \text{ V}, I_{C} = 40 \text{ A}$ | | 1.95 | 2.5 | V |
| Collector-emitter reverse break down voltage | $-V_{CE}$ | $I_C = -100 \text{ mA}, V_{GE} = 15 \text{ V}$ | 18 | 22.5 | | V |
| Short-circuit input capacitance (Common emitter) | Cies | | | 1210 | | pF |
| Short-circuit output capacitance (Common emitter) | C _{oes} | $V_{CE} = 25 \text{ V}, V_{GE} = 0, f = 1 \text{ MHz}$ | | 125 | | pF |
| Reverse transfer capacitance (Common emitter) | C _{res} | | | 21 | | pF |
| Gate charge load | Qg | ,0 | | 51 | | nC |
| Gate-emitter charge | Q_{ge} | $V_{CC} = 250 \text{ V}, I_C = 40 \text{ A}, V_{GE} = 15 \text{ V}$ | | 9 | | nC |
| Gate-collector charge | Q_{gc} | | | 20 | | nC |
| Turn-on delay time | t _{d(on)} | | | 75 | | ns |
| Rise time | t _r | $V_{CC} = 250 \text{ V}, I_{C} = 40 \text{ A},$ $RL \approx 6.25 \Omega, V_{GE} = 15 \text{ V}$ | | 610 | | ns |
| Turn-off delay time | $t_{d(off)}$ | | | 200 | | ns |
| Fall time | t_{f} | | | 185 | 300 | ns |
| Thermal resistance (ch-c) | R _{th(ch-c)} | | | | 3.13 | °C/W |
| Thermal resistance (ch-a) | R _{th(j-a)} | | | | 63 | °C/W |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2PG009 Panasonic



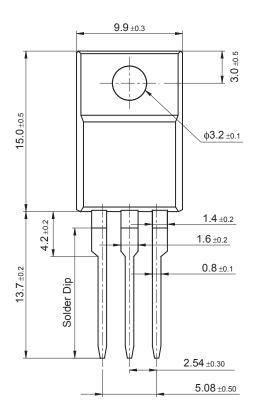


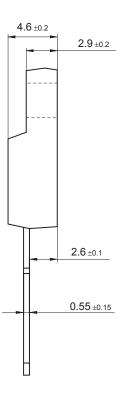
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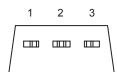
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TO-220D-A1









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